



# H2N6718L

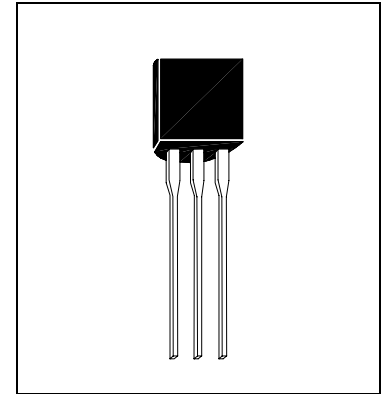
NPN EPITAXIAL PLANAR TRANSISTOR

## Description

The H2N6718L is designed for general purpose medium power amplifier and switching applications.

## Features

- High Power: 850mW
- High Current: 1A



## Absolute Maximum Ratings

- Maximum Temperatures  
Storage Temperature ..... -55 ~ +150 °C  
Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation  
Total Power Dissipation (Ta=25°C) ..... 850 mW
- Maximum Voltages and Currents (Ta=25°C)  
VCBO Collector to Base Voltage ..... 100 V  
VCEO Collector to Emitter Voltage ..... 100 V  
VEBO Emitter to Base Voltage ..... 5 V  
IC Collector Current (Continue) ..... 1 A  
IC Collector Current (Pulse)..... 2 A

## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	100	-	-	V	IC=100uA
BVCEO	100	-	-	V	IC=1mA
BVEBO	5	-	-	V	IE=10uA
ICBO	-	-	100	nA	VCB=80V
*VCE(sat)	-	-	350	mV	IB=35mA, IC=350mA
*hFE1	80	-	-		VCE=1V, IC=50mA
*hFE2	50	-	300		VCE=1V, IC=250mA
*hFE3	20	-	-		VCE=1V, IC=500mA
fT	50	-	-	MHz	VCE=10V, IC=50mA, f=100MHz
Cob	-	-	20	pF	VCB=10V, IE=0, f=1MHz

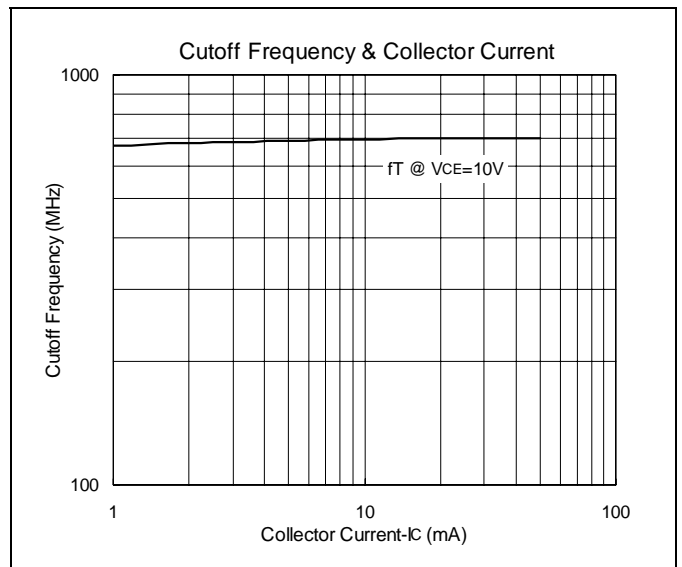
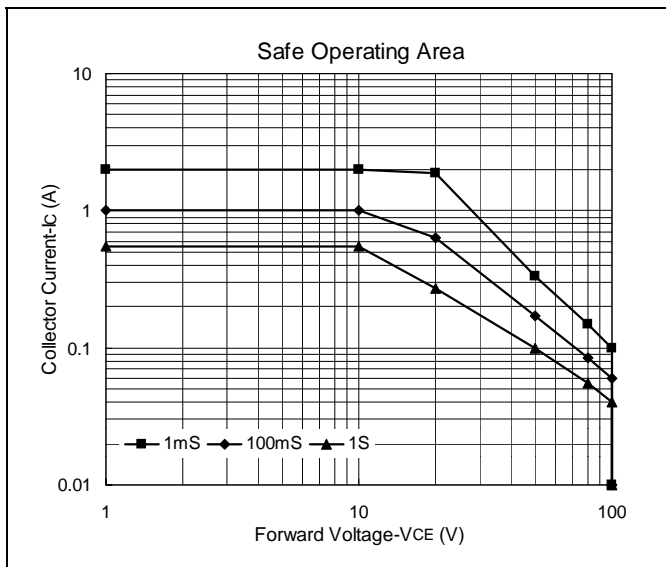
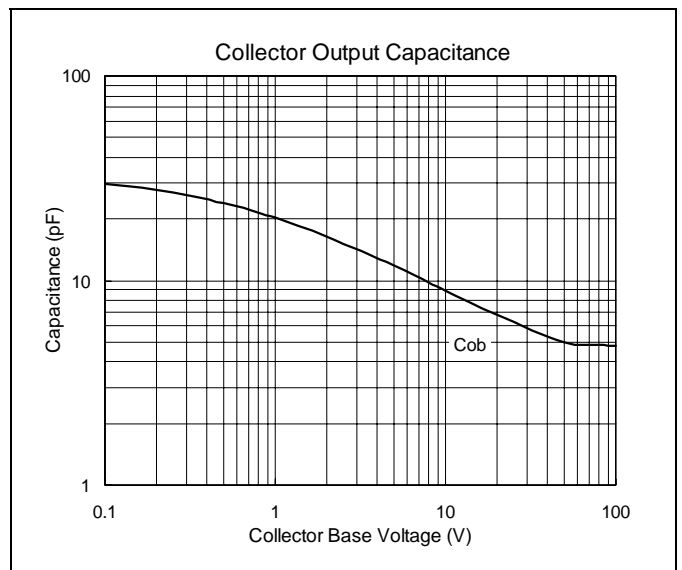
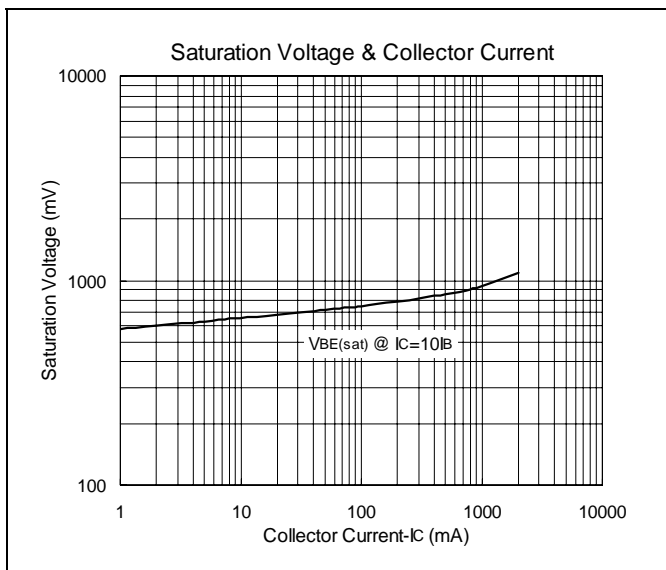
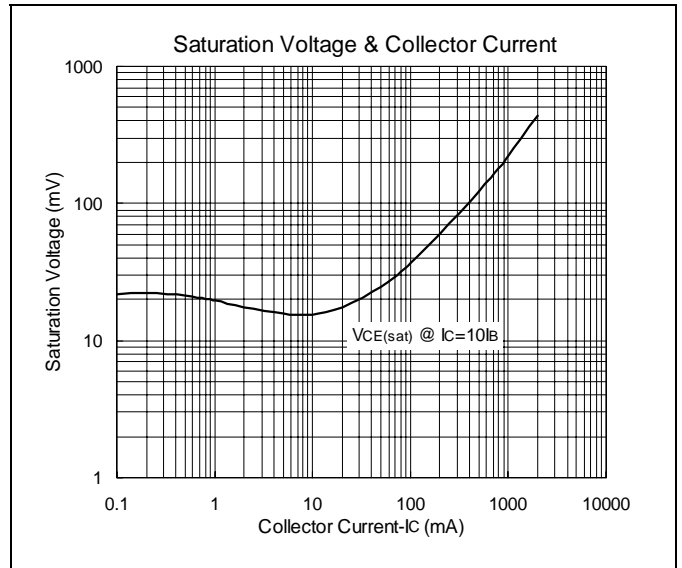
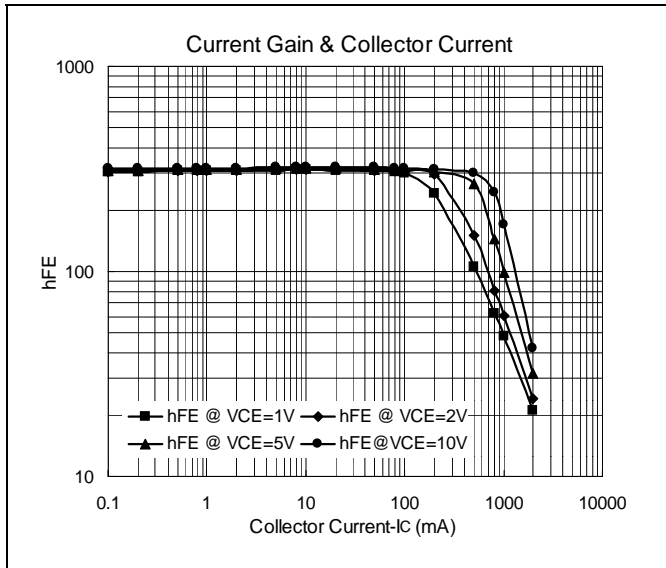
\*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

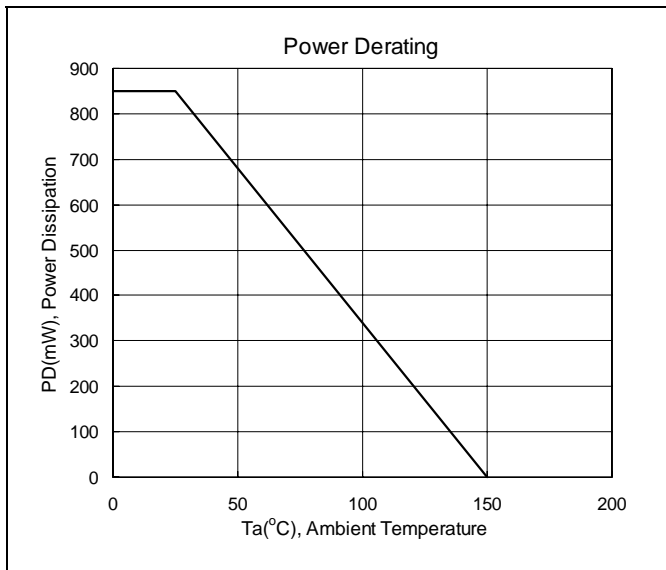
## Classification Of hFE2

Rank	A	B
Range	50-115	95-300



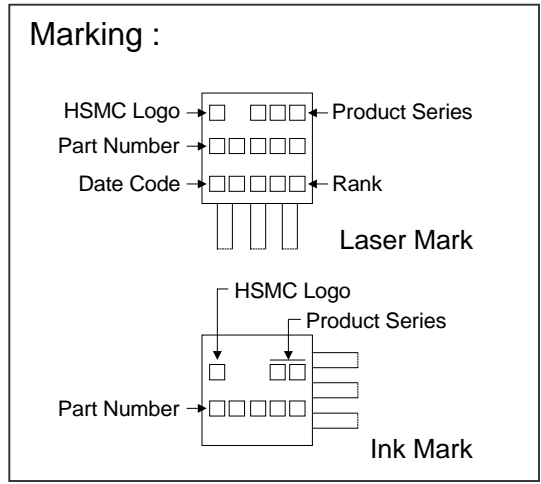
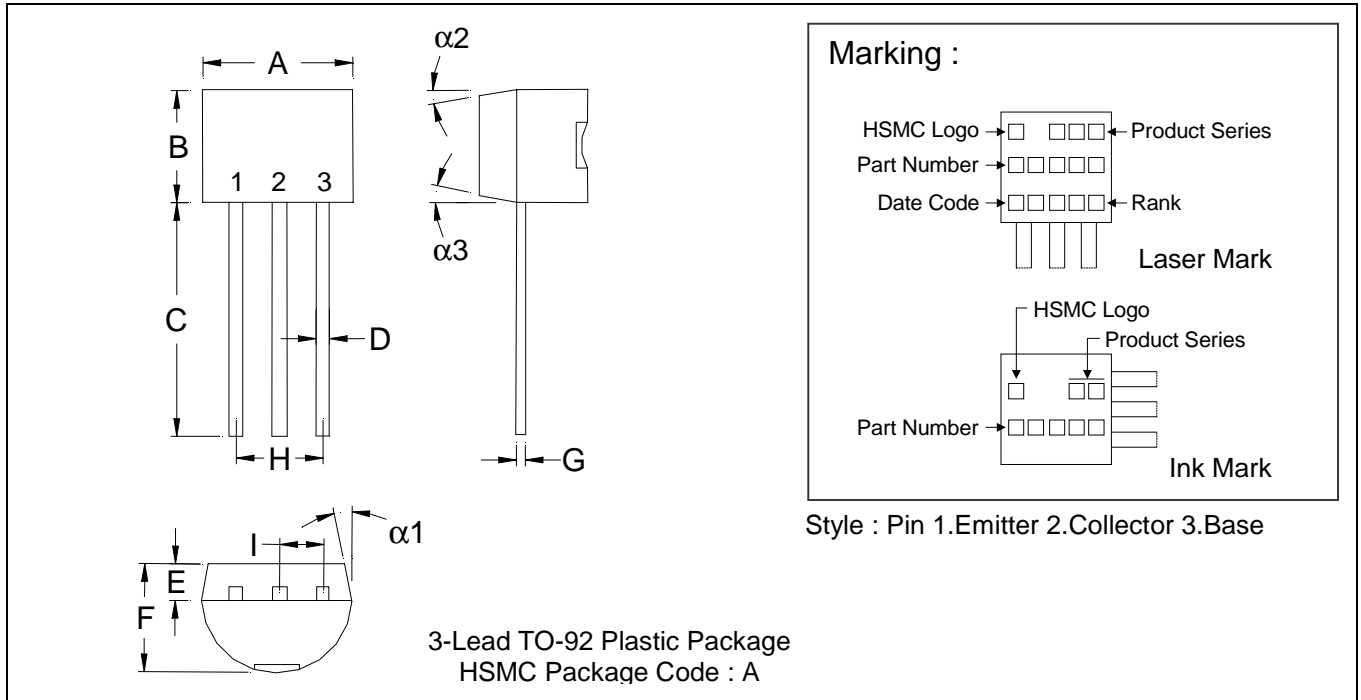
### Characteristics Curve







### TO-92 Dimension



Style : Pin 1. Emitter 2. Collector 3. Base

\*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.  
 2.Controlling dimension : millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material :**

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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